

2004. Acknowledgment of receipt of the certified copy of the priority document is respectfully requested in the next Action.

## **II. Election/Restriction**

Applicants note that the Examiner did not respond to Applicants' remarks in the Amendment filed on October 25, 2005 that claim 2 is a linking claim as defined in MPEP § 809.03. Applicants requested that claim 2 be examined with claim 1 in accordance with MPEP § 809.03 and rejoinder of the process claims 2-5, upon allowance of the product claims 1 and 6-7 and/or linking claim 2. See also MPEP § 821.04 regarding rejoinder of method claims.

For the reasons set forth in the Amendment filed on October 25, 2005, Applicants again request that claim 2 be examined with claim 1 in accordance with MPEP § 809.03. Applicants further request rejoinder of the process claims 2-5, upon allowance of the product claims 1 and 6-7 and/or linking claim 2.

## **III. Response to Rejection under 35 U.S.C. § 102**

Claims 1 and 6 are rejected under 35 U.S.C. § 102(b) as allegedly being anticipated by Igarashi (US Patent 5,990,546).

Applicants respectfully traverse the rejection.

With respect to claim 1, it appears that the Examiner considers bonding sheet 33 in Figure 5(B) of Igarashi et al to be a rubber-containing sheet. However, the material for the bonding sheet material in Figure 5(B) is not disclosed in the reference. Therefore, the Examiner has not set forth a reasonable basis for asserting that the sheet material is rubber and inherently has at least some tackiness. As pointed out in the arguments presented in the

Amendment filed on October 25, 2005, Igarashi et al teaches that the semiconductor chip is sealed by a bonding sheet using an epoxy-rubber resin as a bonding agent. This does not mean that the bonding sheet itself is an epoxy rubber resin and therefore it does not follow that the bonding sheet contains rubber and necessarily has tackiness. Rather, the use of the epoxy-rubber resin as a bonding agent suggests to one of ordinary skill in the art that the bonding sheet itself does not have tackiness.

There is no description in Igarashi et al which teaches or suggests that the bonding sheet itself does contain rubber or has tackiness. Searching the full text of Igarashi et al, the term "rubber" is used only at lines 21 and 37 of column 7 within the context of "a bonding seat [sic] 33 (e.g., epoxy-rubber resin as bonding agent". Thus, a sheet having rubber therein is not taught or suggested.

Moreover, Igarashi et al does not disclose, teach or suggest that the bonding sheet material is thermosetting as recited in independent claim 1. In this regard, the term "thermosetting" is used only at lines 27-28 of column 5 of Igarashi et al in the context of "a thermoplastic or thermosetting bonding agent". Thus, a sheet having a thermosetting property is not taught or suggested.

The present invention is characterized in that a thermosetting sheet material having tackiness is used. A sheet which does not have thermosetting properties cannot be used in the intended application (the field in which appropriate level of thermosetting property is required). Moreover, a mere thermosetting sheet having no tackiness does not exert the effects of the present invention. Therefore, claim 1 is not anticipated nor rendered obvious by the art of record.

Claim 6 depends from claim 1 and is distinguished over the art for at least the same reasons as claim 1. Further, Igarashi et al does not specifically disclose a rubber-containing or rubber-modified polycarbodiimide resin and therefore claim 6 is not anticipated nor rendered obvious by the art of record.

#### **IV. Conclusion**

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

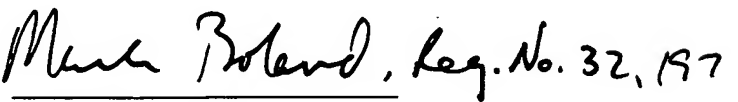
Respectfully submitted,

SUGHRUE MION, PLLC  
Telephone: (202) 293-7060  
Facsimile: (202) 293-7860

WASHINGTON OFFICE

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CUSTOMER NUMBER

  
Jennifer M. Hayes  
Registration No. 40,641

Date: April 5, 2006